



THE BENEFITS ARE CUT AND DRY™

850 E. Industrial Park Drive
Manchester, NH 03109

Ph: 603-644-2326 Fax: 603-647-6889

www.ionbeammilling.com

Metalization Pullback .005" typical
.0005" is possible for special requirements

Laser Machined Features +/- .001"

Annulus .001" Min.
For Plated Through Vias
.002" Min.

Line/Gap Width
.0004" Min.
Tol. +/- .0001"

Typical Radius .006"
Typical Width .020"

.004" +/- .002"
Intrusion

1:1 Aspect Ratio
(Thickness to Diameter)
for Plated Wall Vias



Hole Diameter:
Thru Diameter +/- .002"
Surface Diameter +/- .001"

Hole Location
+/- .001"
(Non-Cumulative)

Laser Cutout
0.006 min.
radius

Metalization
Pullback .002"

Maximum
outside
dimensions
of 4 inches
square

 Resistive Layer
 Conductive Layer

Via to Artwork
Registration
+/- .001"

Min. Via Hole
Separation
.025"

Passivated: Tantalum
Pentoxide for TaN, NiCr
may be Polyimide

Laser Trimmed Layout
at 80% of Normal Value

Resistor Width
.001" Min.

Length
.001" Min.

TaN Resistors
25-200 Ω/Sq.

Layer to Layer
Registration
+/- .0002"

Front to Back
Registration +/- .002

Diamond Blade Diced
+/- .001 L&W Standard

No Overlap on
Conductor Pattern